

**RAJEEV GANDHI MEMORIAL COLLEGE OF ENGINEERING & TECHNOLOGY
(AUTONOMOUS)**

DEPARTMENT OF ELECTRONICS & COMMUNICATION ENGINEERING

SCOPUS INDEXED JOURNALS

AY: 2017-18

1. Pushan Kumar Dutta, K Mallikarjuna, A Sathish “Sensor based solar system using servo motor design for Agro-based automation” International conference on power, control, signals and instrumentation Engineering (ICPCSI-2017).
2. C.Venkataiah, K. Satyaprasad, T. Jayachandra Prasad, “Impact of Supply and Threshold Voltage Scaling on Performance of Cu and CNT Interconnects”, International Journal of Pure and Applied Mathematics, Volume 118 No. 5, pp. 117-126, 2018.
3. T Manasaveena, D Satyanarayana, MN Giri Prasad, “A novel saliency mapping approach for joint multiview video plus depth coding” International Conference on Intelligent Communication and Computational Techniques (ICCT), DEC 2017, PP 205-210.
4. C.Venkataiah Dr. T. Jaya Chandra Prasad, & K. Satya Prasad, “ Effect of Line Parasitic Variations on Delay and Energy of Global On-Chip VLSI Interconnects in DSM Technology” Springer International conference on microelectronics, electromagnetic and telecommunications(ICMEET), Visakhapatnam, India, January, 2017.
5. N Ramanjaneyulu et all “ A 3.4 Ghz Fast Locking Pll Using Transmission Gae charge pump in 0.18um Cmos for Hdmi Applications” APRN journal Engineering and Applied Science, May 2017,Vol 13,PP 2815-2829
6. AVasavi, ”Technology And Instrumentation System For Characterization Of MyoPotetial A”, International Journal of Pure and Applied Mathematics, Volume 117, No. 18 2017, Pg.NO: 357-366, ISSN: 1311-8080 (printed version); ISSN: 1314-3395 (on-line version), SCOPUS Published. H-Index is 17
7. Dr.V Ramesh Kumar et all “Design of Novel Through Silicon via Structures for Reduced Crosstalk Effects in 3D IC Applications” Intelligent Communication, Control and

Devices, Advances in Intelligent Systems and Computing, Dec 2018, Vol 624,pp-599-605

8. Dr.V Ramesh Kumar et all “Effect of Skin Impedance on Delay and Crosstalk in Lossy and Non-uniform On-Chip Interconnects” Intelligent Communication, Control and Devices, Advances in Intelligent Systems and Computing, Dec 2018, Vol 624,pp-569-576.